



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

IPC-1752-1 v1.01
1752-1

IPC Web Site for Information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type *
Distribute

Declaration Class *
Class 1 - RoHS Yes/No

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	Response Date *	Response Document ID					
Contemporary Controls	363857474	FEIN	2006-07-28	MCD_PC10420_CXB.pdf					
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *						
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Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *		Supplier Comments or URL for Additional Information				
Neil Maloney	Manufacturing Engineer	(630) 963-7070	rohs@ccontrols.com						
	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Type
	PC10420-CXB	PC10420-CXB	COM200020	2006-07-01		Downers Grove, USA	77	g	Each
	Alternate Recommendation				Alternate Item Comments				

Manufacturing Information section intentionally omitted.

Save the fields in this form to a file

Export Data

Import fields from a file into this form

Import Data

Locked

RoHS Material Composition Declaration

Declaration Type *

Custom

RoHS Directive 2002/95/EC **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Contemporary Control Systems, Incorporated certifies that all Contemporary Controls products that are RoHS compliant shall be labeled on both the product serial number label and the product box label as: **RoHS** ✓
Any product without this label designation is considered either non RoHS compliant or RoHS status unknown.

RoHS Declaration *

4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions

Supplier Acceptance

Accepted

Exemptions: The items on this form meet the specifications of the RoHS Definition above, except for the following application-specific exemptions. Check the appropriate boxes below for the applicable exemptions for the item.

- 1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp
- 2a. Mercury in straight fluorescent lamps for general purposes not exceeding 10 mg in halophosphate lamps
- 2b. Mercury in straight fluorescent lamps for general purposes not exceeding 5 mg in triphosphate lamps with a normal lifetime
- 2c. Mercury in straight fluorescent lamps for general purposes not exceeding 8 mg in triphosphate with long lifetime
- 3. Mercury in straight fluorescent lamps for special purposes
- 4. Mercury in other lamps not specifically mentioned in this list
- 5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes
- 6a. Lead as an alloying element in steel containing up to 0.35% lead by weight
- 6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight
- 6c. Lead as an alloying element in copper containing up to 4% lead by weight
- 7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead)
- 7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications
- 7c. Lead in electronic ceramic parts (e.g. piezoelectronic devices)
- 8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances
- 9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators
- 10a. DecaBDE in polymeric applications
- 10b. Lead in lead-bronze bearing shells and bushes
- 11. Lead used in compliant pin connector systems
- 12. Lead as a coating material for a thermal conduction module c-ring
- 13a. Lead in optical and filter glass
- 13b. Cadmium in optical and filter glass
- 14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight
- 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Neil Maloney

Digitally signed by Neil Maloney
DN: cn=Neil Maloney, o=US, ou=Contemporary Controls, ou=Manufacturing Engineer,
email=nmaloney@cccontrols.com
Date: 2006.07.31 16:46:51 -0500

JIG section intentionally omitted.